

Abstract

The present disclosure provides a through electrode substrate intermediate comprising: a glass substrate including a first surface and a second surface facing the first surface, and including a through hole; a through electrode disposed in the through hole of the glass substrate; an elastic insulating layer disposed on a first surface side of the glass substrate; a via passing through the elastic insulating layer, and electrically connected to the through electrode; a pad portion for a via disposed on a surface of the elastic insulating layer that is opposite side to the glass substrate, and electrically connected to the via; and a pad portion for connecting a wiring board disposed on a surface of the elastic insulating layer that is opposite side to the glass substrate, and to be electrically connected to a wiring board, wherein the elastic insulating layer has a convexoconcave shape, including a plurality of convex portions and a plurality of concave portions, on a surface that is on a side of the pad portion for a via and the pad portion for connecting a wiring board.